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| 1. Plating Thickness | Electro Nickel Ni: 1.27 – 8.89 micron (Solder Pads) Electro Gold Au: 0.70-1.20 micron (Solder Pads) |
| 2. Connection | 1-VC, 2-INHN, 3-VSS-S/R, 4-Q, 5-VDD-D/A, 6-XT, 7-XTN, 8-INHN2 |
| 3. Camber | 50.00 micron maximum |
| Exposure of ceramic surface occurring by misalignment of the upper layer shall be allowed. | |
| ■ indicates the side metalized pattern | |
| Stress Relaxation design shall be applied on this item | |
| Sealing Method of this product shall be seam weld. | |

| Type | Sub-type | Description | | S5070VCX02 |
|----------|----------|-------------|------|------------|
| Design | Check | Approved | Rev. | |
| AB | ER | TH | A | |
| 11/23/04 | | | | VC America |